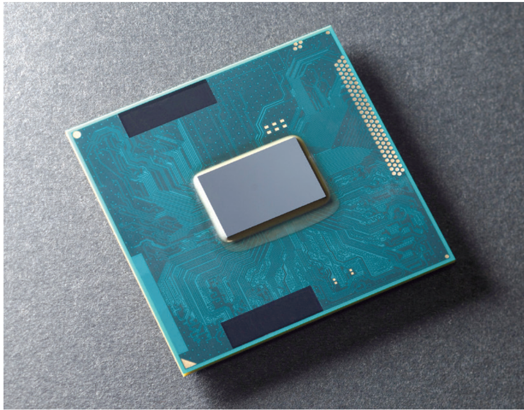
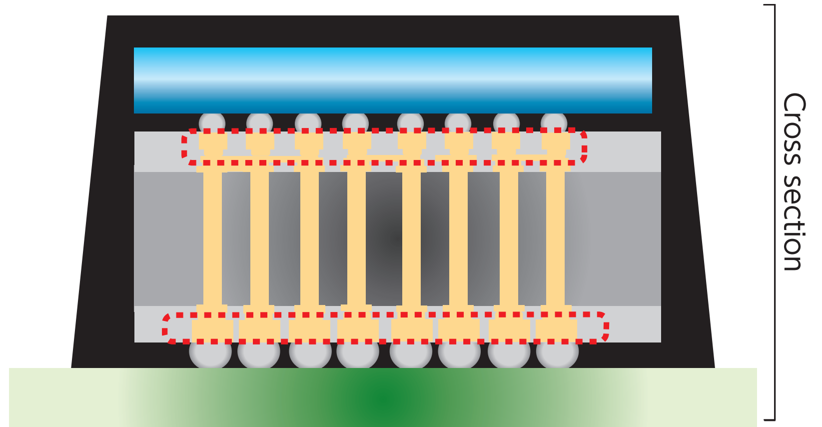
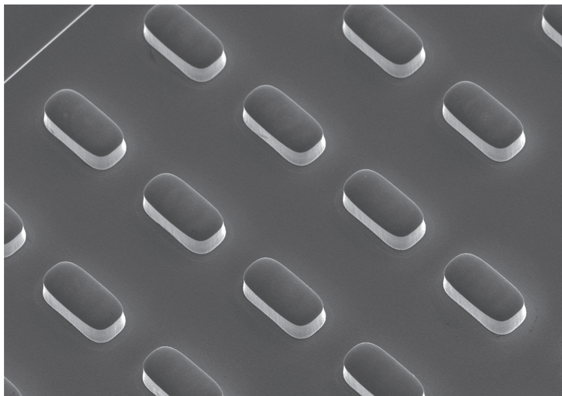
Acid copper plating additive to FO-PLP/WLP for high current density, copper bump formation

TOP LUCINA SP



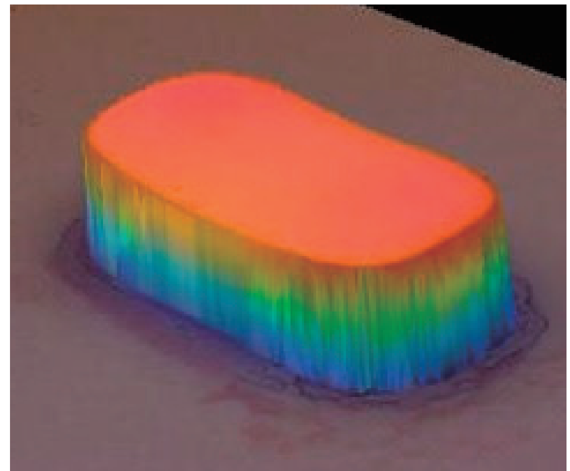


Uniform height of bump

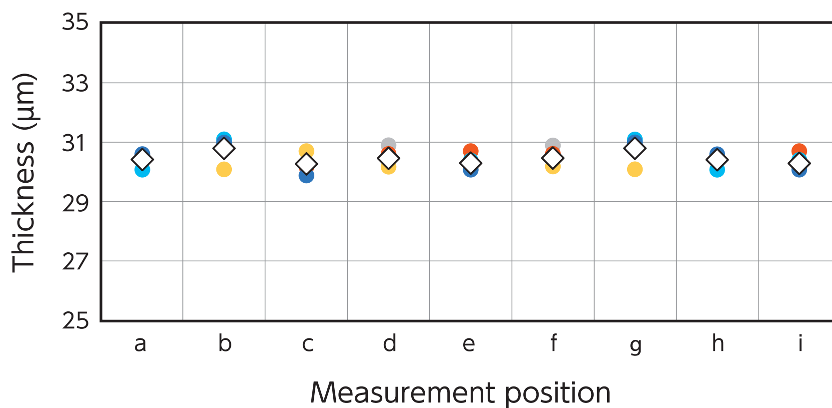


Current density: 5 A/dm²
Pillar height: 30 μm
Wafer size: 6 inch

Flat surface formation



Uniform surface thickness



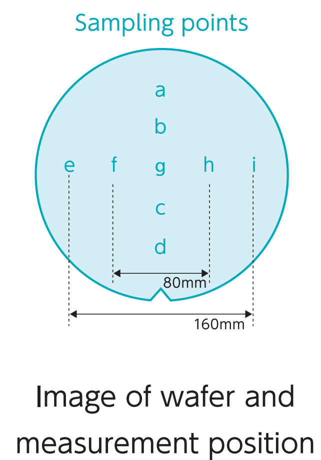


Image of wafer and measurement position